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United States Patent [19]

Farnworth et al.

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[54] **TEMPORARY PACKAGE FOR SEMICONDUCTOR DICE**

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[73] Assignee: **Micron Technology, Inc.**, Boise, Id.

[**] Term: **14 Years**

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[51] **LOC (6) Cl.** **13-03**

[52] **U.S. Cl.** **D13/182**

[58] **Field of Search** D14/114; D13/182; 257/668, 671, 672, 693; 174/52.1-52.5; 439/55, 70; 361/718, 820

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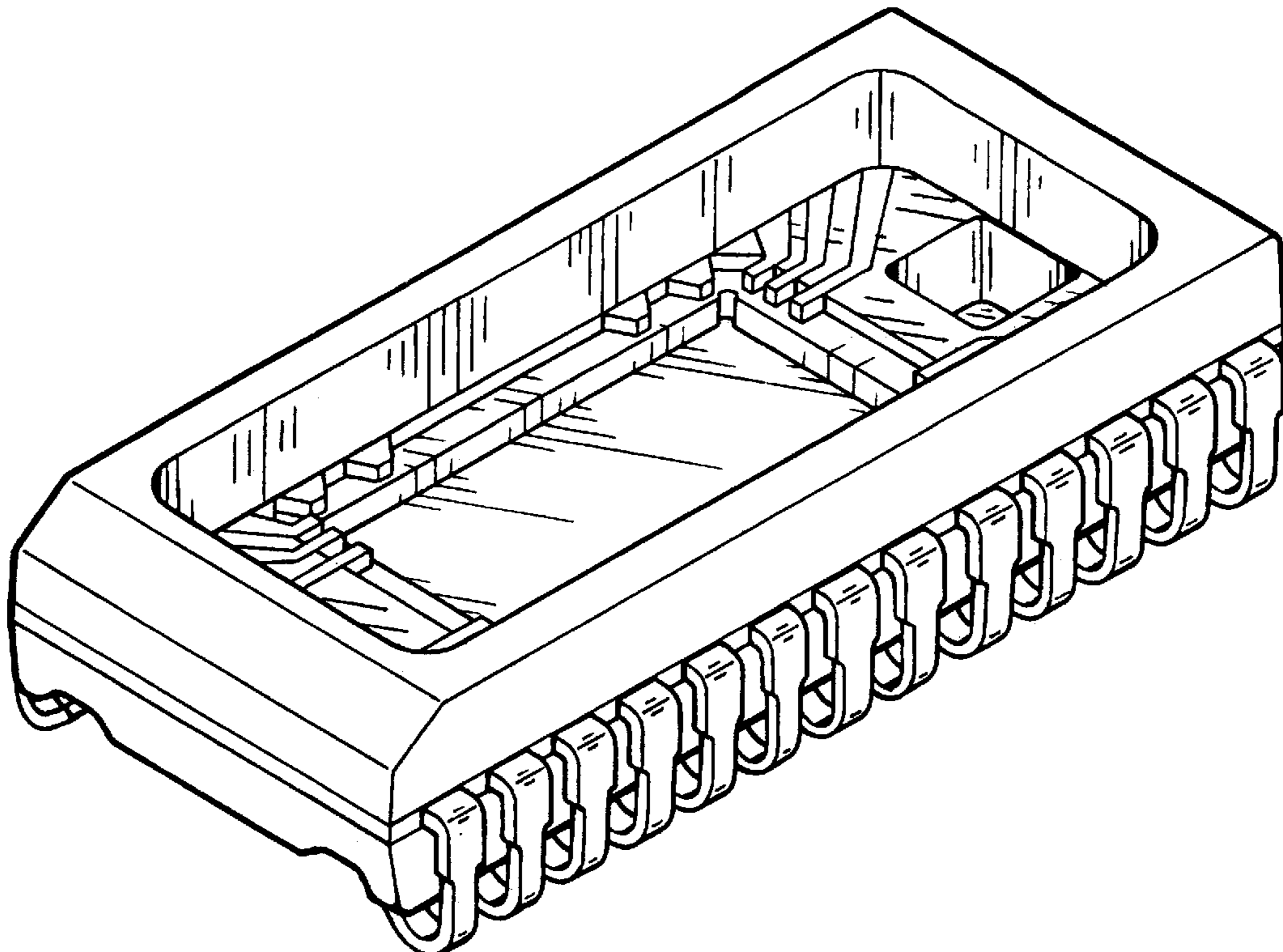
[57] **CLAIM**

The ornamental design for a temporary package for semiconductor dice, as shown and described.

DESCRIPTION

FIG. 1 is an enlarged top perspective view of a temporary package for semiconductor dice showing our new design; FIG. 2 is a left side elevational view thereof; FIG. 3 is a right side elevational view thereof; FIG. 4 is a top plan view thereof; FIG. 5 is a front side elevational view thereof; FIG. 6 is a bottom plan view thereof; and, FIG. 7 is a rear side elevation view thereof.

1 Claim, 2 Drawing Sheets



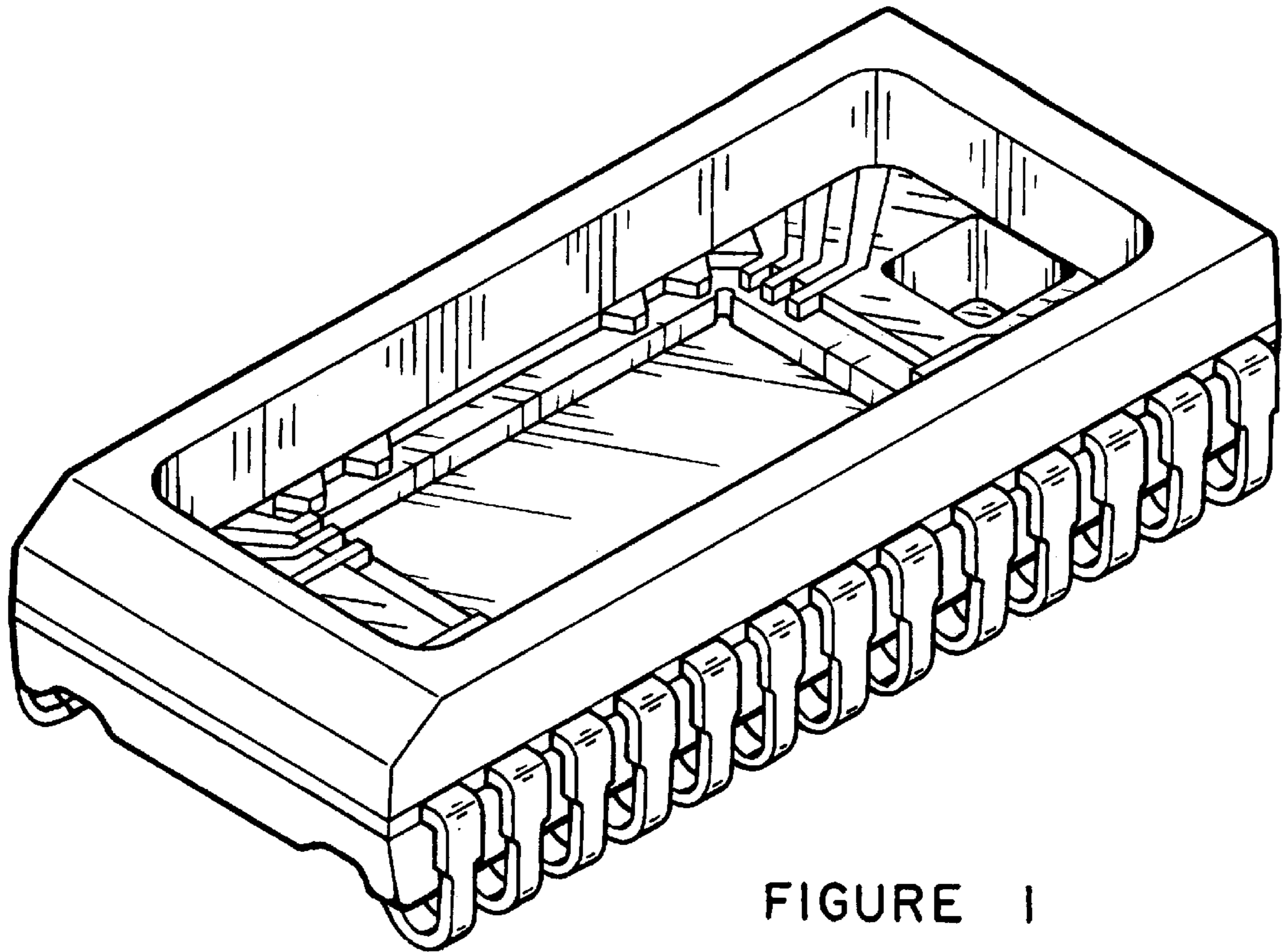


FIGURE 1

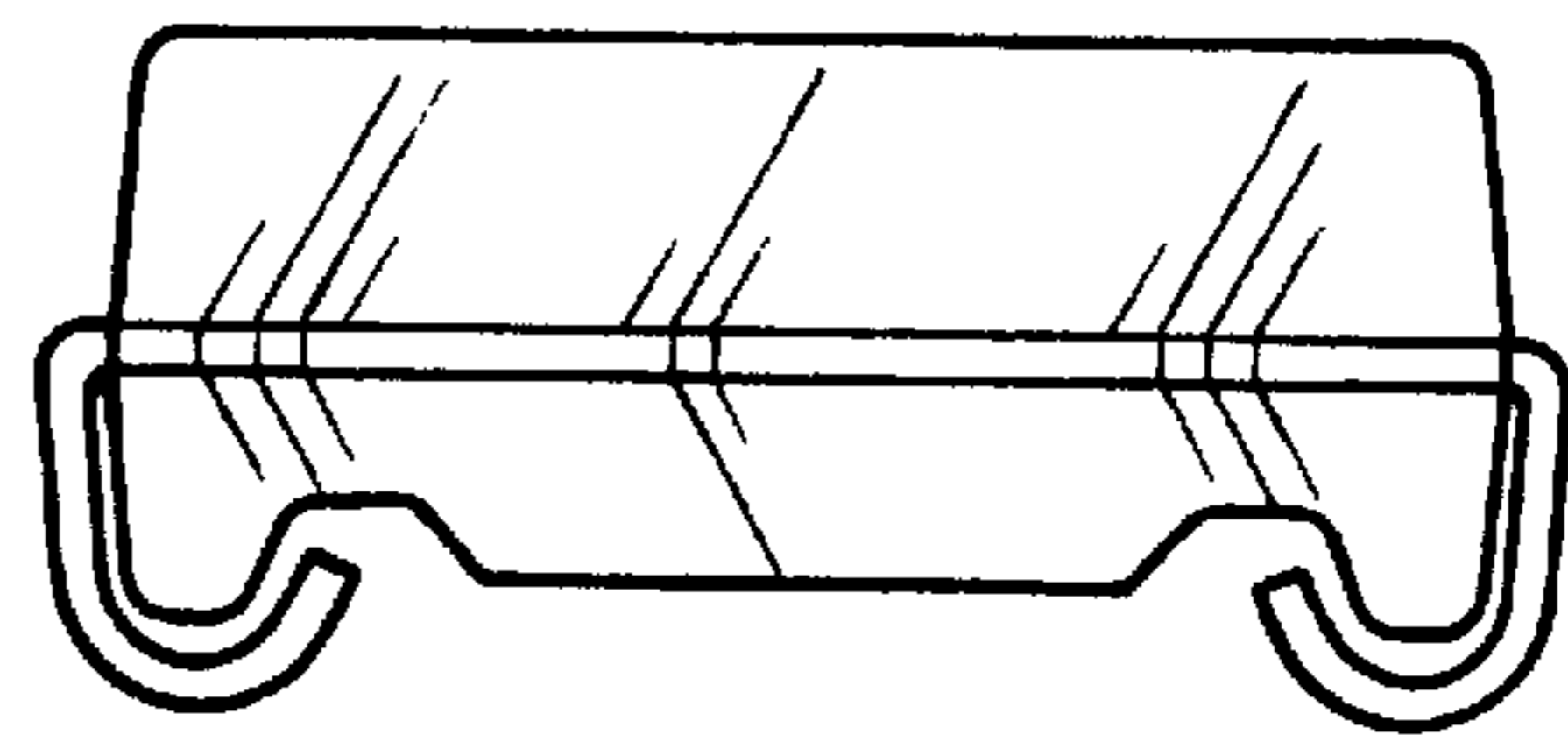


FIGURE 2

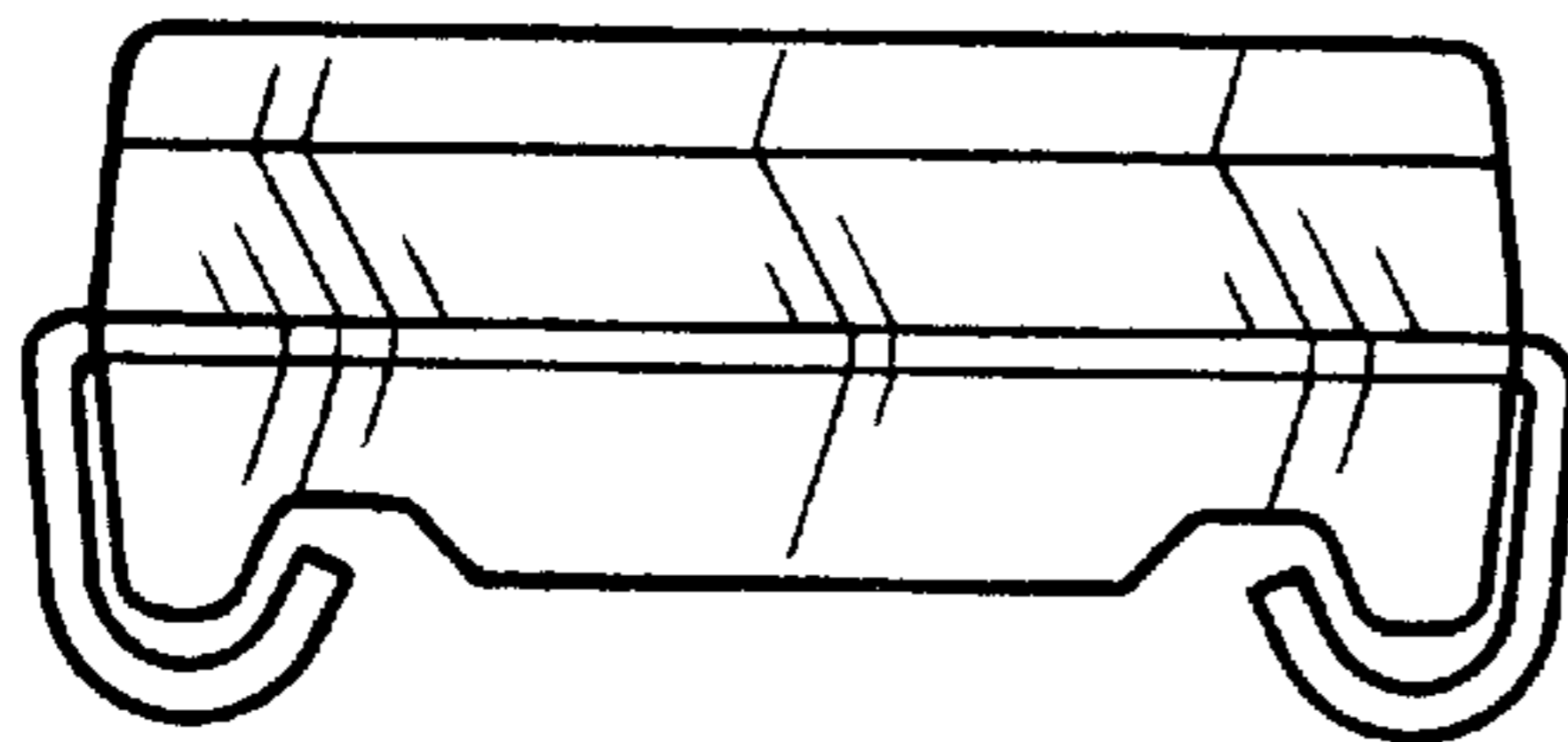


FIGURE 3

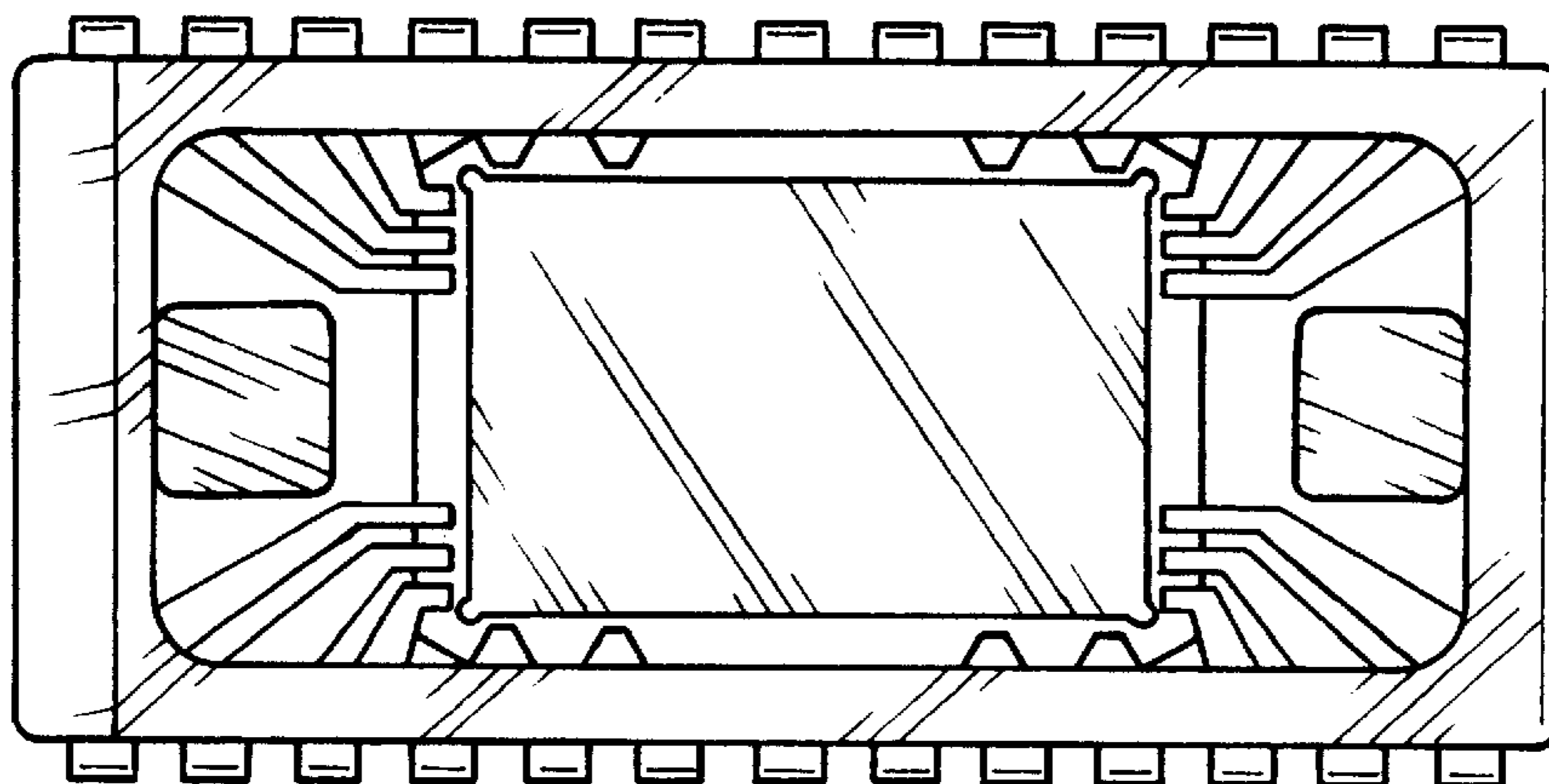


FIGURE 4

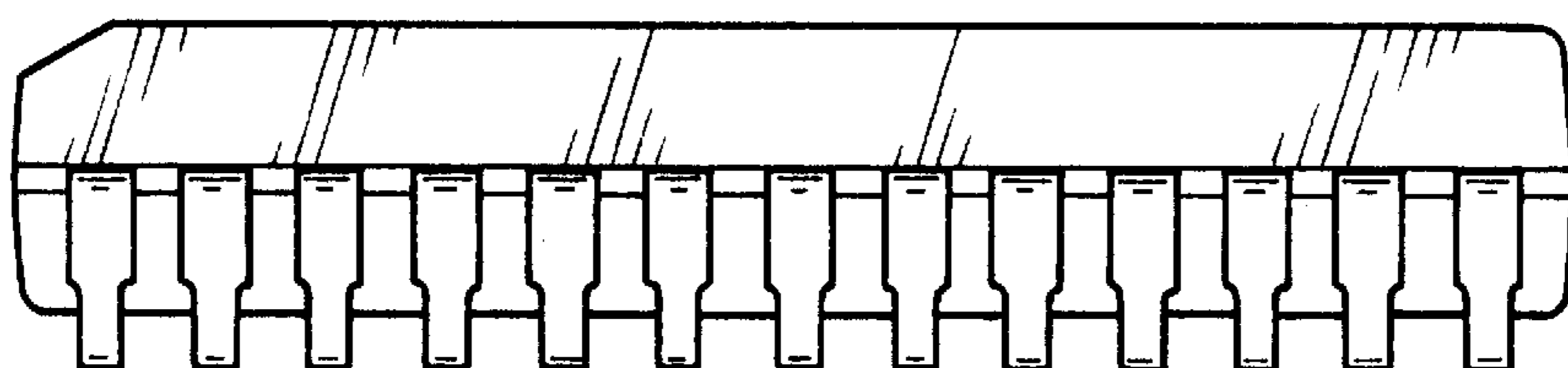


FIGURE 5

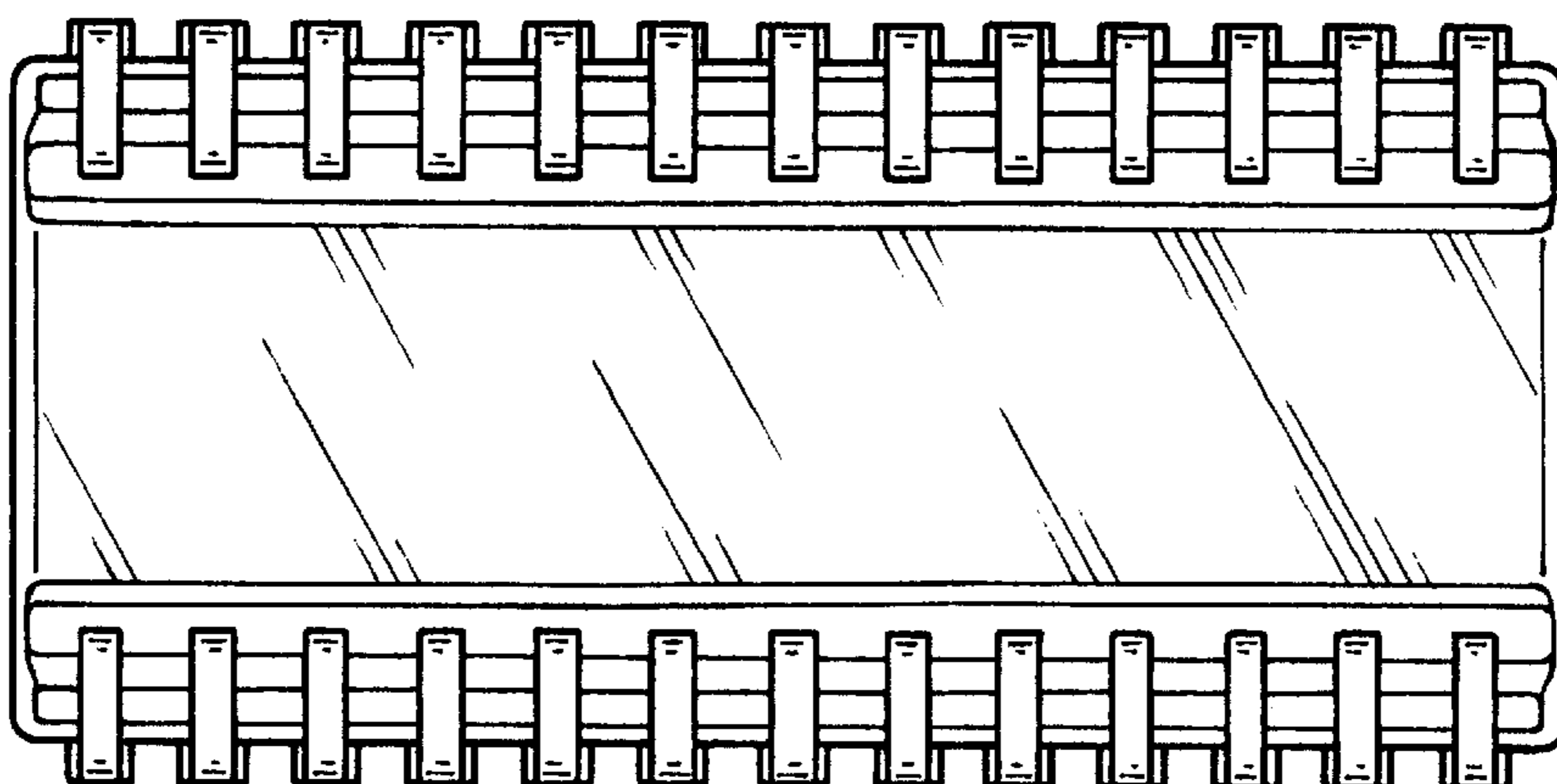


FIGURE 6

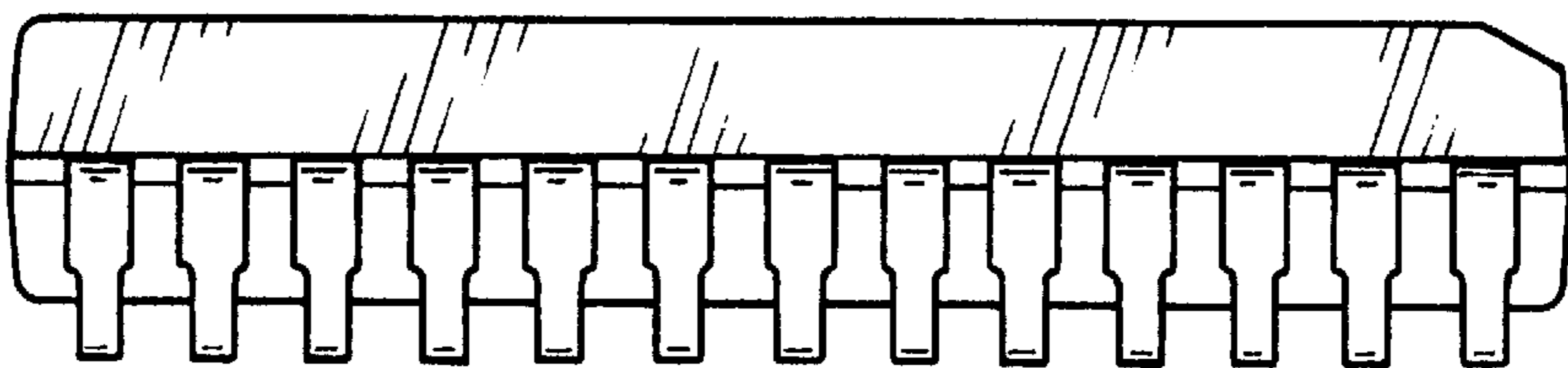


FIGURE 7